

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

1. (Currently Amended) Electro spray source having a structure comprising at least one flat and thin tip (3) in cantilever in relation to the rest of the structure, said tip (3) being provided with a capillary slot (5) formed through the complete thickness of the tip and which ends up at the end (6) of the tip (3) to form the ejection orifice of the electro spray source, the source comprising means of supplying (4) the capillary slot (5) with liquid to be nebulised and means of applying an electro spray voltage to said liquid.
2. (Currently Amended) Electro spray source according to claim 1, ~~characterised in that~~ wherein the supply means comprise at least one reservoir (4) in fluidic communication with the capillary slot (5).
3. (Currently Amended) Electro spray source according to claim 1, ~~characterised in that~~ wherein the structure comprises a support (1) and a wafer (2) integral with the support and in which a part constitutes said tip (3).
4. (Currently Amended) Electro spray source according to claim 3, ~~characterised in that~~ wherein the supply means comprise a reservoir (4) constituted by a recess formed in said wafer (2) and in fluidic communication with the capillary slot (5).
5. (Currently Amended) Electro spray source according to ~~any of claims 1 to 4,~~ claim 1, wherein the means of applying an electro spray voltage comprise at least one electrode (7, 8) arranged so as to be in contact with said liquid to be nebulised.

6. (Currently Amended) Electrospray source according to ~~any of claims 3 or 4, characterised in that~~ claim 3, wherein the means of applying an electrospray voltage comprise the support, at least partially electrically conductive, and/or the wafer at least partially electrically conductive.

7. (Currently Amended) Electrospray source according to ~~any of claims 1 to 4, characterised in that~~ claim 1, wherein the means of applying an electrospray voltage comprise an electrically conductive wire (32) arranged in order to be able to be in contact with said liquid to be nebulised.

8. (Currently Amended) Electrospray source according to ~~any of claims 1 to 7, characterised in that~~ claim 1, wherein the supply means comprise a capillary tube.

9. (Currently Amended) Electrospray source according to ~~any of claims 1 to 7, characterised in that~~ claim 1, wherein the supply means comprise a channel formed in a microsystem supporting said structure and in fluidic communication with the capillary slot.

10. (Currently Amended) Electrospray source according to ~~one of claims 3 or 4, characterised in that~~ claim 3, wherein the wafer (2) has a surface hydrophobic to the liquid to be nebulised.

11. (Currently Amended) Method of manufacturing a structure being an electrospray source, comprising:

- the formation of a support (1) from a substrate (10),
- the formation of a wafer (2) having a part constituting a flat and thin tip (3), said tip being provided with a capillary slot (5), to convey a liquid to be nebulised, formed in the complete thickness of the tip and which ends up the end of the tip,
- making said wafer (2) integral on the support (1), the tip (3) being in cantilever in relation to the support.

12. (Currently Amended) Method according to claim 11, ~~characterised in that~~ wherein it comprises the following steps:

- the provision of a substrate (10) to form the support (1),
- the delimitation of the support (1) by means of trenches (13) etched in the substrate (10),
- the deposition, on a zone of the substrate corresponding to the future tip of the structure, of sacrificial material (14) according to a determined thickness,
- the deposition of the wafer (2) on the support (1) delimited in the substrate (10), the tip (3) of the wafer (2) being situated on the sacrificial material (14),
- the elimination of the sacrificial material (14),
- the detachment of the support (1) in relation to the substrate (10) by cleavage at the level of said trenches (13).

13. (Currently Amended) Method according to claim 12, ~~characterised in that~~ wherein the step of deposition of the wafer (2) is a deposition of a wafer comprising a recess in fluidic communication with the capillary slot (5) in order to constitute a reservoir (4).

14. (Currently Amended) Method according to ~~one of claims 12 or 13,~~ claim 12, wherein it further comprises a step of depositing at least one electrode (7, 8) intended to assure an electrical contact with the liquid to be nebulised.

Claims 15. – 18 (Canceled)

19. (New) Ionization of a liquid by electrospraying the liquid with the electrospray source of claim 1, and analyzing the changed liquid by mass spectrometry.

20. (New) Producing drops of liquid of a calibrated or controlled size by electrospraying a liquid using the electrospray source of claim 1.

21. (New) Carrying out molecular writing with chemical compounds by electrospraying chemical compounds using the electrospray source of claim 1.

22. (New) Electro spraying a liquid using the electrospray source of claim 1 to define the electrical junction potential of a device in fluidic continuity.